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Qualified for Automotive Applications

Typical V<sub>OLP</sub> (Output Ground Bounce)
 <0.8 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C

- Typical V<sub>OHV</sub> (Output V<sub>OH</sub> Undershoot)
  >2.3 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- Supports Mixed-Mode Voltage Operation on All Ports
- I<sub>off</sub> Supports Partial-Power-Down Mode Operation
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

#### description/ordering information

This hex Schmitt-trigger inverter is designed for 2-V to 5.5-V V<sub>CC</sub> operation.

The SN74LV14A contains six independent inverters. This device performs the Boolean function  $Y = \overline{A}$ .

This device is fully specified for partial-power-down applications using I<sub>off</sub>. The I<sub>off</sub> circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

#### **ORDERING INFORMATION<sup>†</sup>**

T <sub>A</sub>	PACK	AGE‡	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 105°C	TSSOP – PW	Tape and reel	SN74LV14ATPWRQ1	LV14ATQ

<sup>†</sup> For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.

<sup>‡</sup> Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

FUNCTION TABLE (each inverter)										
INPUT A	OUTPUT Y									
н	L									
L	Н									

#### logic diagram, each inverter (positive logic)





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



F		PACH OP VI		
1A [	<b>1</b>	$\mathbf{O}$	14	
1Y	2		13	] V <sub>CC</sub> ] 6A
2A [	3		12	07 67
27 [ 2Y [	4		11	5A
3A [	5		10	5Y
3Y [	6		9	4A
GND [	7		0	1 4A 1 4Y
GND	1		0	U 4 Y

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#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub>	–0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high-impedance	
or power-off state, V <sub>O</sub> (see Note 1)	–0.5 V to 7 V
Output voltage range, V <sub>O</sub> (see Notes 1 and 2)	–0.5 V to V <sub>CC</sub> + 0.5 V
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	–50 mA
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$	±25 mA
Continuous current through V <sub>CC</sub> or GND	±50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 3)	113°C/W
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

2. This value is limited to 5.5 V maximum.

3. The package thermal impedance is calculated in accordance with JESD 51-7.

#### recommended operating conditions (see Note 4)

			MIN	МАХ	UNIT
V <sub>CC</sub>	Supply voltage		2	5.5	V
		$V_{CC} = 2 V$	1.5		
.,	Little Land Second configure	$V_{CC}$ = 2.3 V to 2.7 V	$V_{CC}  imes 0.7$		.,
VIH	High-level input voltage	V <sub>CC</sub> = 3 V to 3.6 V	$V_{CC}  imes 0.7$		V
		$V_{CC} = 4.5 V \text{ to } 5.5 V$	$V_{CC}  imes 0.7$		
		$V_{CC} = 2 V$		0.5	
.,		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		$V_{CC}  imes 0.3$	v
VIL	Low-level input voltage	V <sub>CC</sub> = 3 V to 3.6 V		$V_{CC}\!\times\!0.3$	V
		$V_{CC} = 4.5 V \text{ to } 5.5 V$		$V_{CC}\!\times\!0.3$	
VI	Input voltage		0	5.5	V
Vo	Output voltage		0	V <sub>CC</sub>	V
		$V_{CC} = 2 V$		-50	μA
	Link land autout autout	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		-2	
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 3 V to 3.6 V		-6	mA
		$V_{CC} = 4.5 V \text{ to } 5.5 V$		-12	
		V <sub>CC</sub> = 2 V		50	μA
		$V_{CC}$ = 2.3 V to 2.7 V		2	mA
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 3 V to 3.6 V		6	
		$V_{CC}$ = 4.5 V to 5.5 V		12	
T <sub>A</sub>	Operating free-air temperature		-40	105	°C

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP	MAX	UNIT	
V <sub>T+</sub>		2.5 V			1.75		
Positive-going		3.3 V			2.31	V	
threshold		5 V			3.5		
V <sub>T-</sub>		2.5 V	0.75				
Negative-going		3.3 V	0.99			V	
threshold		5 V	1.5				
		2.5 V	0.25		1		
$\Delta V_{T}$ Hysteresis (V <sub>T+</sub> – V <sub>T-</sub> )		3.3 V	0.33		1.32	V	
$  y_3 c  c_{3 3} ( v_{ +} -  v_{ -} )$		5 V	0.5		2		
	I <sub>OH</sub> = -50 μA	2 V to 5.5 V	V <sub>CC</sub> -0.1				
N.	I <sub>OH</sub> = -2 mA	2.3 V	2			.,	
V <sub>OH</sub>	I <sub>OH</sub> = -6 mA	3 V	2.48			V	
	I <sub>OH</sub> = -12 mA	4.5 V	3.8				
	I <sub>OL</sub> = 50 μA	2 V to 5.5 V			0.1		
N.	$I_{OL} = 2 \text{ mA}$	2.3 V			0.4	.,	
V <sub>OL</sub>	$I_{OL} = 6 \text{ mA}$	3 V			0.44	V	
	I <sub>OL</sub> = 12 mA	4.5 V			0.55		
l	$V_{I} = V_{CC}$ or GND	0 V to 5.5 V			±1	μA	
I <sub>CC</sub>	$V_{I} = V_{CC}$ or GND,	<sub>O</sub> = 0 5.5 V			20	μA	
l <sub>off</sub>	$V_{I}$ or $V_{O} = 0$ to 5.5 V	0 V			5	μA	
•		3.3 V		2.3		5	
Ci	$V_{I} = V_{CC} \text{ or } GND$	5 V		2.3		pF	

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER		FROM	то	LOAD	T,	₄ = 25°C		MAINI	MAX	
	PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	ТҮР	MAX	MIN	MAX	UNIT
	t <sub>pd</sub>	А	Y	$C_L = 50 \text{ pF}$		9.6	16.3	1	20.4	ns

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	LOAD	T,	₄ = 25°C		RAINI	MAX	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	ТҮР	MAX	MIN	MAX	UNIT
t <sub>pd</sub>	А	Y	$C_L = 50 \text{ pF}$		6.7	10.6	1	14	ns



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# noise characteristics, $V_{CC}$ = 3.3 V, $C_L$ = 50 pF, $T_A$ = 25°C (see Note 5)

PARAMETER	MIN	ТҮР	MAX	UNIT
Quiet output, maximum dynamic V <sub>OL</sub>		0.2	0.8	V
Quiet output, minimum dynamic V <sub>OL</sub>		-0.1	-0.8	V
Quiet output, minimum dynamic V <sub>OH</sub>		3.1		V
High-level dynamic input voltage	2.31			V
Low-level dynamic input voltage			0.99	V
	Quiet output, maximum dynamic V <sub>OL</sub> Quiet output, minimum dynamic V <sub>OL</sub> Quiet output, minimum dynamic V <sub>OH</sub> High-level dynamic input voltage	Quiet output, maximum dynamic V <sub>OL</sub> Image: Color of the second secon	Quiet output, maximum dynamic V <sub>OL</sub> 0.2      Quiet output, minimum dynamic V <sub>OL</sub> -0.1      Quiet output, minimum dynamic V <sub>OH</sub> 3.1      High-level dynamic input voltage    2.31	Quiet output, maximum dynamic V <sub>OL</sub> 0.2    0.8      Quiet output, minimum dynamic V <sub>OL</sub> -0.1    -0.8      Quiet output, minimum dynamic V <sub>OH</sub> 3.1    -0.1      High-level dynamic input voltage    2.31    -0.1

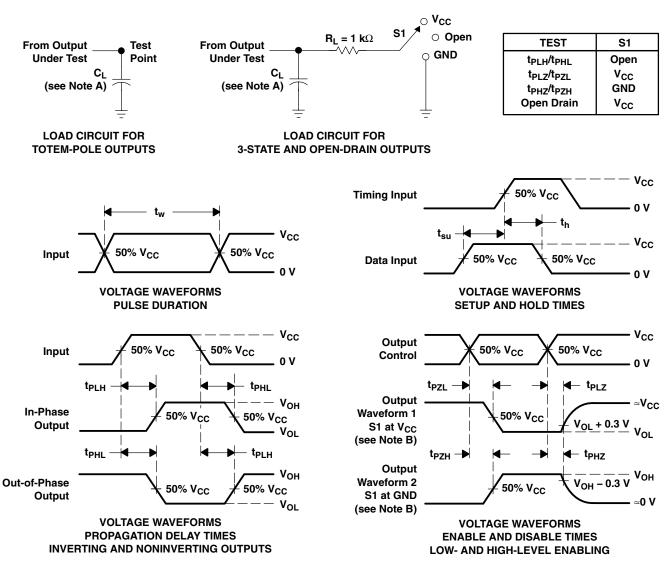
NOTE 5: Characteristics are for surface-mount packages only.

## operating characteristics, $T_A$ = 25°C

		PARAMETER	TEST CO	NDITIONS	V <sub>CC</sub>	ТҮР	UNIT
	Power die	sipation capacitance	C <sub>1</sub> = 50 pF,	f = 10 MHz	3.3 V	8.8	۶F
C	d Poweruis	sipation capacitance	C <sub>L</sub> = 50 p⊢,		5 V	9.6	рг



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### PARAMETER MEASUREMENT INFORMATION

NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>r</sub>  $\leq$  3 ns, t<sub>f</sub>  $\leq$  3 ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- G.  $t_{PHL}$  and  $t_{PLH}$  are the same as  $t_{pd}$ .
- H. All parameters and waveforms are not applicable to all devices.

#### Figure 1. Load Circuit and Voltage Waveforms





24-Jan-2013

### PACKAGING INFORMATION

Orderable Device	Status	Package Type	•	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
	(1)		Drawing			(2)		(3)		(4)	
SN74LV14ATPWRG4Q1	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 105	LV14ATQ	Samples
SN74LV14ATPWRQ1	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 105	LV14ATQ	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between

the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> Only one of markings shown within the brackets will appear on the physical device.

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#### OTHER QUALIFIED VERSIONS OF SN74LV14A-Q1 :

Catalog: SN74LV14A





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Enhanced Product: SN74LV14A-EP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Enhanced Product Supports Defense, Aerospace and Medical Applications

## PACKAGE MATERIALS INFORMATION

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### TAPE AND REEL INFORMATION





## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV14ATPWRG4Q1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV14ATPWRQ1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

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## PACKAGE MATERIALS INFORMATION

14-Mar-2013



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV14ATPWRG4Q1	TSSOP	PW	14	2000	367.0	367.0	35.0
SN74LV14ATPWRQ1	TSSOP	PW	14	2000	367.0	367.0	35.0

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



A. An integration of the information o

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.

Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

E. Falls within JEDEC MO-153



# PW (R-PDSO-G14)

# PLASTIC SMALL OUTLINE



- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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